

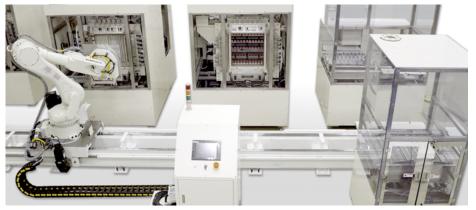
## NOVEL VERTICAL CUP PLATING

**FAN-OUT PANEL LEVEL PACKAGING FOR RDL METALLIZATION** 



# Novel Vertical Cup Plating

**Fan-Out Panel Level Packaging for RDL Metallization** 



Plating Line Integrated with Automation System



Self-Designed Gripper

## **TECHNICAL SPECIFICATIONS**

## NOVEL VERTICAL CUP COPPER PLATING

Dimensions (L $\times$ W $\times$ H)	Customizable
Panel Size (mm)	510 x 515 up to 720 x 650
Anode	Insoluble/Single or Multiple Zone
Convection/Agitation	Fan Type or Eductor Type
Membrance	Ionic Exchange Membrance
Warpage allowance	5~10 mm
Cathode Contact Failure Detection	Yes
Blanket UN%	<10%
Through Hole/Via, Filling Capability	Down to 25um
Pattern UN%	<15%

### **DESCRIPTION**

Process flow: Loading→Micro Etch→Acid Rinse→Cu Plating→Water Rinse
 →Dry→Unloading
 Type of carrier substrate: Stainless, Epoxy, Glass & CCL(FR-4)
 Fully integrated with automation system
 Modular design
 Jia free

Specific performance parameters depend on the application.

#### **FEATURES**

Unique jig free design reduces the chemical consumption & saves the maintenance cost.

No void defect for through hole or via.

Excellent plating uniformity <10% for larger panels and small via  $(<25\mu m)$  filling capabilities.

Highly integrated with automation system including loading/unloading.

Integrated with upstream & downstream processes including pre-treatment, plating & post-cleaning.

Modular design optimizes the production and maintenance efficiency.